

L Number	Hits	Search Text	DB	Time stamp
1	1	"20030052418"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/08 09:32
2	40999	mold near2 {upper lower}	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/08 09:41
3	1694	{mold near2 {upper lower}} and semiconductor and {chip die wafer}	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/08 09:42
4	446	{{mold near2 {upper lower}} and semiconductor and {chip die wafer}} and {leadframe {lead near1 {inner outer}}}	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/08 09:45
5	395	{{{mold near2 {upper lower}} and semiconductor and {chip die wafer}} and {leadframe {lead near1 {inner outer}}} and {sealing sealed encapsulant encapsulating encapsulated}}	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/08 12:18
6	369	{{{{mold near2 {upper lower}} and semiconductor and {chip die wafer}} and {leadframe {lead near1 {inner outer}}} and {sealing sealed encapsulant encapsulating encapsulated}} and {method process}}	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/08 09:47
7	122	{{{{mold near2 {upper lower}} and semiconductor and {chip die wafer}} and {leadframe {lead near1 {inner outer}}} and {sealing sealed encapsulant encapsulating encapsulated}} and {method process}} and {{die mounting} adj; pad}	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/08 09:47
8	53	5474958.URPN.	USPAT	2003/05/08 09:52
9	0	6472252.URPN.	USPAT	2003/05/08 09:59
10	36	("4313718" "4697784" "4881884" "4944908" "5147821" "5355283" "5362679" "5405255" "5406699" "5467253" "5468999" "5474958" "5477611" "5479051" "5490324" "5506756" "5508565" "5527743" "5543658" "5545922" "5556807" "5596227" "5609889" "5626886" "5656549" "5663106" "5665281" "5688716" "5766643" "5766650" "5817545" "5876765" "5923959" "5928595" "6117382" "6281588").PN.	USPAT USPAT USPAT	2003/05/08 09:52 2003/05/08 09:59 2003/05/08 09:59
11	3	6117382.URPN.	USPAT	2003/05/08 10:01
12	20	("5034350" "5114880" "5147815" "5222014" "5239806" "5313365" "5331205" "5366364" "5458694" "5488257" "5578261" "5597643" "5598034" "5608262" "5609889" "5614441" "5615089" "5646829" "5755914" "5830781").PN.	USPAT USPAT	2003/05/08 10:01 2003/05/08 10:02
13	20	("5034350" "5114880" "5147815" "5222014" "5239806" "5313365" "5331205" "5366364" "5458694" "5488257" "5578261" "5597643" "5598034" "5608262" "5609889" "5614441" "5615089" "5646829" "5755914" "5830781").PN.	USPAT	2003/05/08 10:04
14	7	5923959.URPN.	USPAT	2003/05/08 10:05
15	20	("5355283" "5362679" "5406699" "5467253" "5468999" "5474958" "5477611" "5479051" "5490324" "5506756" "5508565" "5527743" "5543658" "5545922" "5556807" "5596227" "5609889" "5656549" "5663106" "5688716").PN.	USPAT USPAT	2003/05/08 10:10 2003/05/08 10:10
16	21	5609889.URPN.	USPAT	2003/05/08 10:12

17	0	6428300.URPN.	USPAT	2003/05/08 10:13
18	29	("3505446" "3685784" "3991146" "4184835" "4464322" "4470786" "4618466" "4770833" "4954308" "5049344" "5049526" "5110515" "5174941" "5326243" "5344600" "5366368" "5429488" "5451153" "5480296" "5523038" "5558883" "5609889" "5626886" "5650177" "5714106" "5798070" "5989471" "6030569" "6224360").PN.	USPAT USPAT	2003/05/08 10:13
21	26	5817545.URPN.	USPAT	2003/05/08 10:18
22	0	6558982.URPN.	USPAT	2003/05/08 10:19
23	6	("5817545" "5874324" "5998243" "6204095" "6329224" "6335221").PN.	USPAT	2003/05/08 10:19
24	36	("3930114" "4043027" "4437141" "4455274" "4460537" "4470786" "4688152" "4778641" "4823234" "4859722" "4861251" "4868349" "4890152" "4893172" "4935581" "4954877" "4954878" "4961105" "4972253" "4975765" "5019673" "5049526" "5093282" "5108955" "5132778" "5136366" "5153385" "5191511" "5216278" "5218759" "5241133" "5296738" "5328870" "5355283" "5370517" "5395226").PN.	USPAT	2003/05/08 10:23
25	40	5108955.URPN.	USPAT	2003/05/08 10:26
26	7	("4266239" "4541005" "4778641" "4822550" "4823234" "4868638" "4890152").PN.	USPAT USPAT	2003/05/08 10:43
27	3	6081978.URPN.	USPAT	2003/05/08 12:10
28	3	("5336272" "6001671" "6033933").PN.	USPAT	2003/05/08 12:11
29	113	((((mold near2 (upper lower)) and semiconductor and (chip die wafer)) and (leadframe (lead near1 (inner outer)))) and (sealing sealed encapsulant encapsulating encapsulated)) and (vent vacuum))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/08 12:18
30	389176	"113" not ((((((mold near2 (upper lower)) and semiconductor and (chip die wafer)) and (leadframe (lead near1 (inner outer)))) and (sealing sealed encapsulant encapsulating encapsulated)) and (method process)) and ((die mounting) adj pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/08 12:19
31	91	(((((mold near2 (upper lower)) and semiconductor and (chip die wafer)) and (leadframe (lead near1 (inner outer)))) and (sealing sealed encapsulant encapsulating encapsulated)) and (vent vacuum)) not ((((((mold near2 (upper lower)) and semiconductor and (chip die wafer)) and (leadframe (lead near1 (inner outer)))) and (sealing sealed encapsulant encapsulating encapsulated)) and (method process)) and ((die mounting) adj pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/05/08 12:19
32	25	5147821.URPN.	USPAT	2003/05/08 12:24
33	2	("4866506" "4944908").PN.	USPAT	2003/05/08 12:26
118	25	5147821.URPN.	USPAT	2003/05/08 13:43
119	53	5474958.URPN.	USPAT	2003/05/08 13:44
120	4	5776800.URPN.	USPAT	2003/05/08 13:45
121	5	("5101324" "5130889" "5309026" "5394298" "5474958").PN.	USPAT USPAT	2003/05/08 13:45
122	2	5874319.URPN.	USPAT	2003/05/08 13:48
123	21	("3777365" "3811182" "4881885" "4932883" "5147821" "5173451" "5203401" "5237269" "5322207" "5336649" "5367253" "5378981" "5424652" "5459351" "5474958" "5475317" "5489538" "5548884" "5568057" "5589781" "5591649").PN.	USPAT USPAT	2003/05/08 13:48
126	2	("4866506" "4944908").PN.	USPAT	2003/05/08 13:53

[27] [27 ("4866506" | "4944908").PN.] [USPAT] [2003/05/08 13:53]